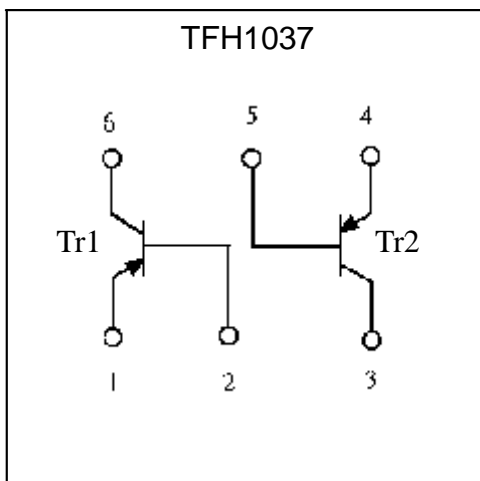


TFH1037

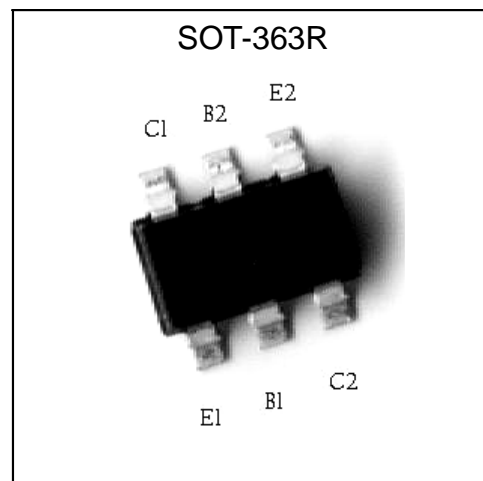
Features

- Two TFS1037 chips in a SOT-363R package.
- Mounting possible with SOT-323 automatic mounting machines.
- Transistor elements are independent, eliminating interference.
- Mounting cost and area can be cut in half.
- Excellent hFE linearity
- Complementary to TFH2412.
- Pb-free package

Equivalent Circuit



Outline



The following characteristics apply to both Tr1 and Tr2

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V _{CBO}	-60	V
Collector-Emitter Voltage	V _{CEO}	-50	V
Emitter-Base Voltage	V _{EBO}	-6	V
Collector Current	I _C	-150	mA
Power Dissipation	P _d	200(total) *1	mW
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55~+150	°C

Note : *1 150mW per element must not be exceeded



Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-60	-	-	V	IC=-50μA
BVCEO	-50	-	-	V	IC=-1mA
BVEBO	-6	-	-	V	IE=-50μA
ICBO	-	-	-0.1	μA	VCB=-60V
IEBO	-	-	-0.1	μA	VEB=-6V
*VCE(sat)	-	-0.2	-0.5	V	IC=-50mA, IB=-5mA
*hFE	200	-	560		VCE=-6V, IC=-1mA
fT	80	180	-	MHz	VCE=-10V, IC=-1mA, f=100MHz
Cob	-	2	3.5	pF	VCB=-10V, f=1MHz

*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

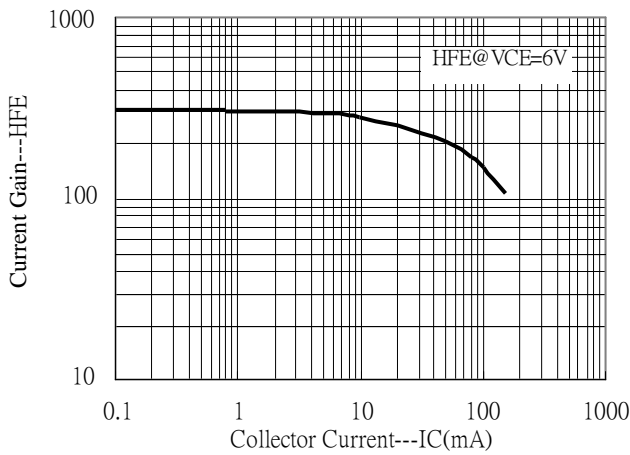
Ordering Information

Device	Package	Shipping	Marking
TFH1037	SOT-363 (Pb-free)	3000 pcs / Tape & Reel	A2

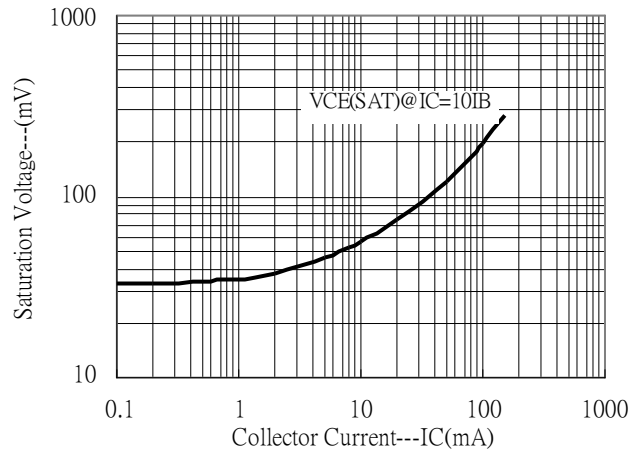


Characteristic Curves

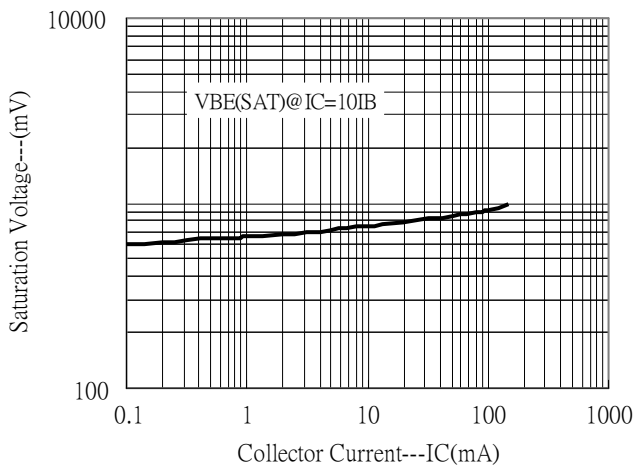
Current Gain vs Collector Current



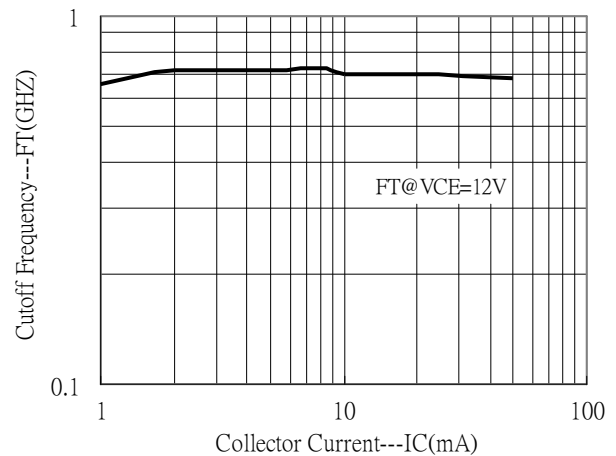
Saturation Voltage vs Collector Current



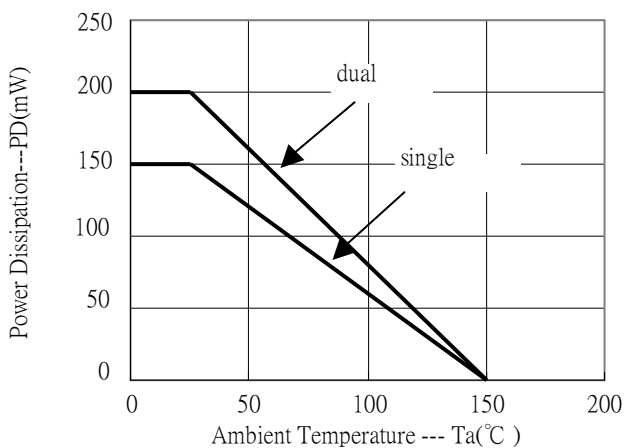
Saturation Voltage vs Collector Current



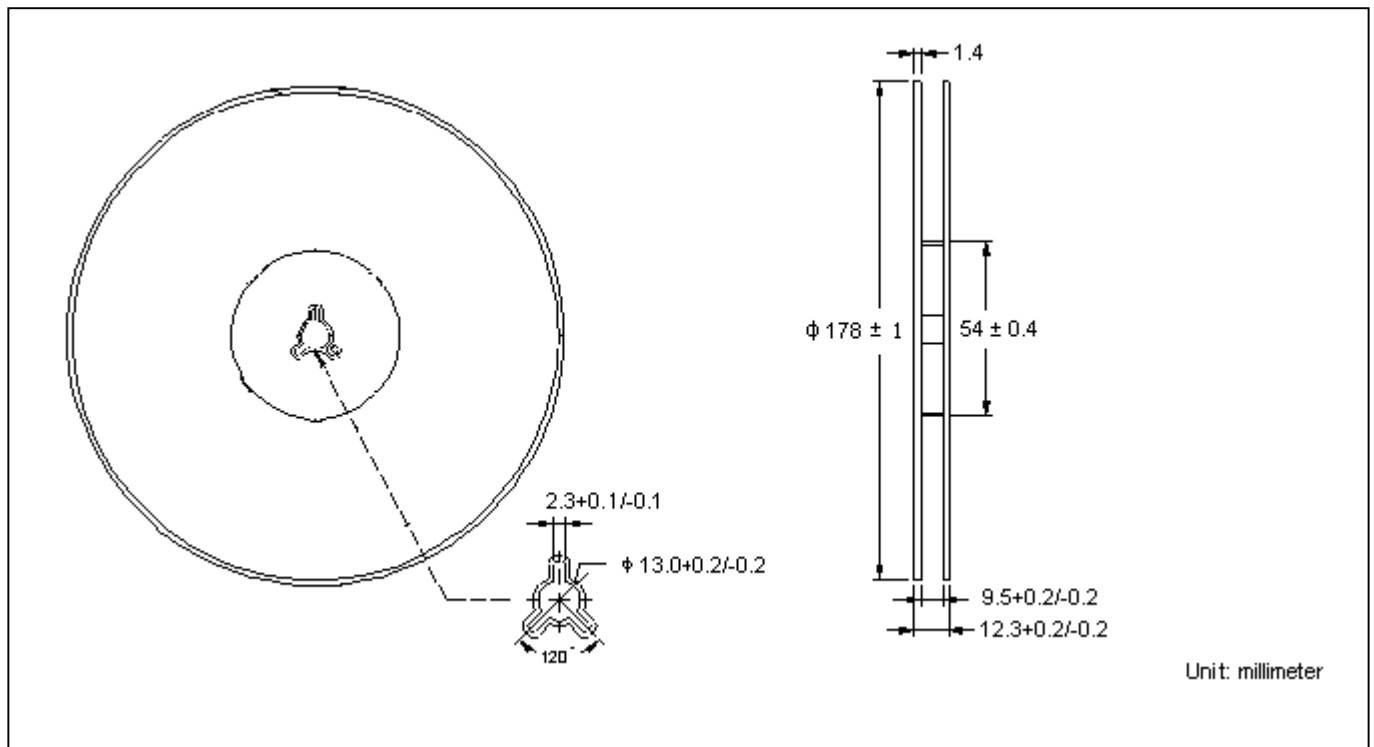
Cutoff Frequency vs Collector Current



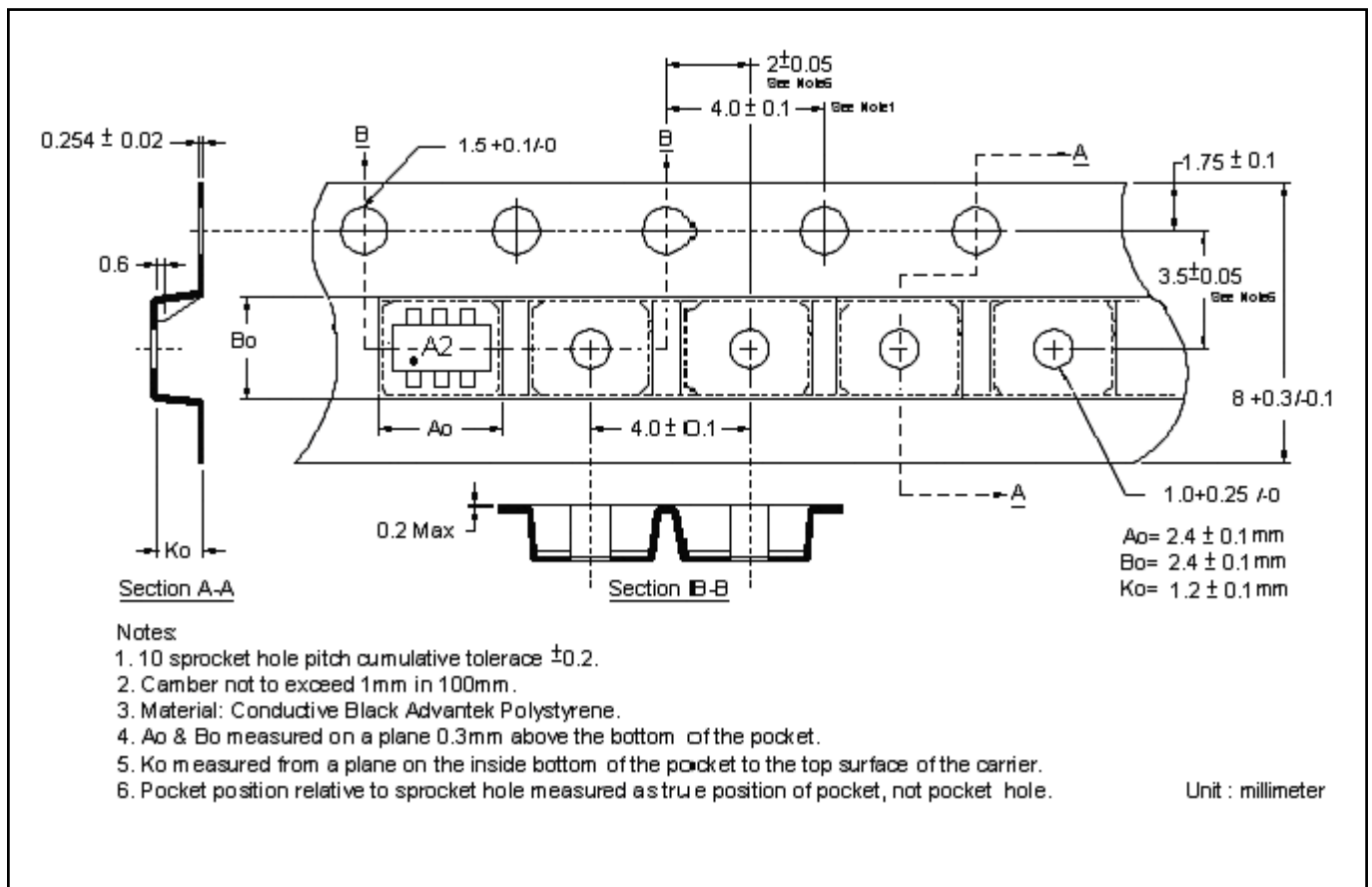
Power Derating Curves



Reel Dimension



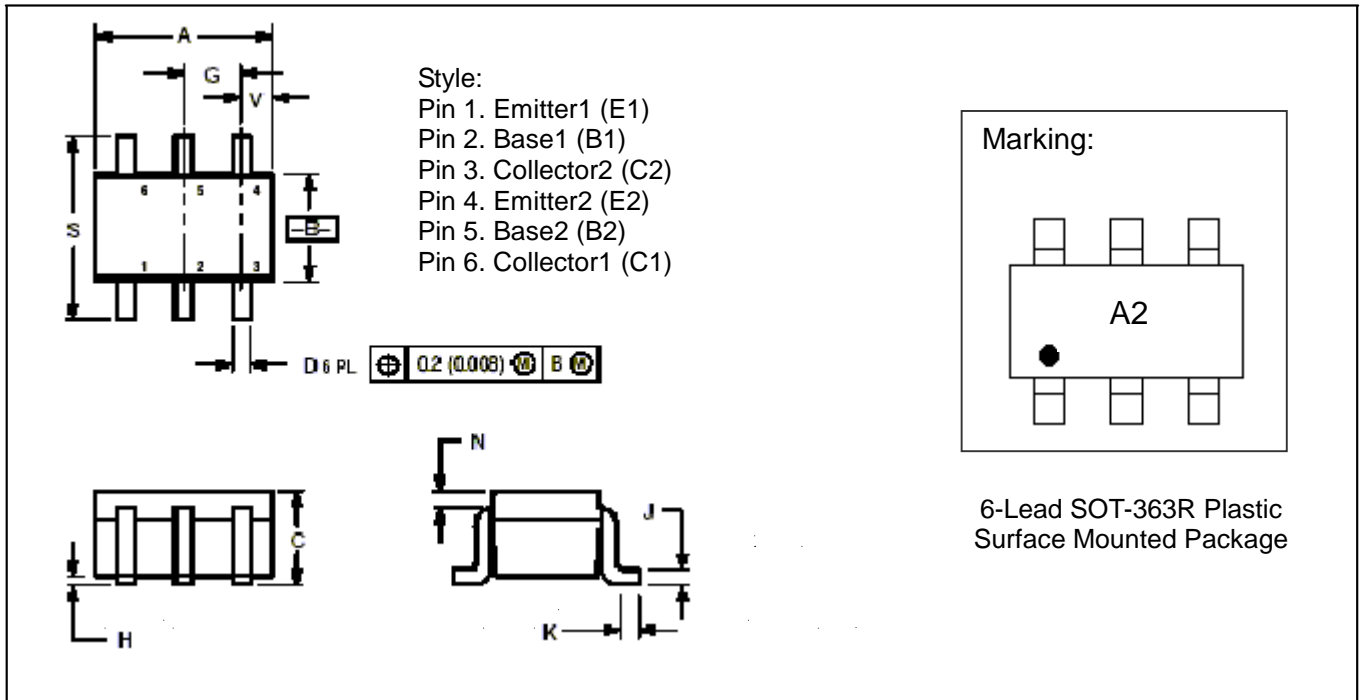
Carrier Tape Dimension



Notes:

1. 10 sprocket hole pitch cumulative tolerance ± 0.2 .
2. Camber not to exceed 1mm in 100mm.
3. Material: Conductive Black Advantek Polystyrene.
4. A_0 & B_0 measured on a plane 0.3mm above the bottom of the pocket.
5. K_0 measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

SOT-363R Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.071	0.087	1.8	2.2	J	0.004	0.010	0.1	0.25
B	0.045	0.053	1.15	1.35	K	0.004	0.012	0.1	0.30
C	0.031	0.043	0.8	1.1	N	0.008 REF		0.20 REF	
D	0.004	0.012	0.1	0.3	S	0.079	0.087	2.00	2.40
G	0.026BSC		0.65BSC		Y	0.012	0.016	0.30	0.40
H	-	0.004	-	0.1					

- Notes : 1.Controlling dimension : millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local Tin Far sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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